

APPARATUS AND METHOD FOR THIN DIE DETACHMENT

ABSTRACT

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The invention provides an apparatus and method for thin die detachment involving the use of a collet for holding and detaching a die mounted on an adhesive surface of an adhesive film. An ejector device comprising a plurality of ejector pins is employed to partially delaminate said die from the adhesive surface for detachment by the collet. Each ejector pin is operative to contact and raise a second surface of the film opposite the adhesive surface at a position substantially at a corner of the die to be detached within a predetermined distance from the edges of said die.

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15 (Figure 3)